

# 應用於半加成製程的先進除膠渣程序及酒石酸系化學沉銅技術

## Advanced Desmear / Rochel Salt Electroless Copper for Semi-Additive Process

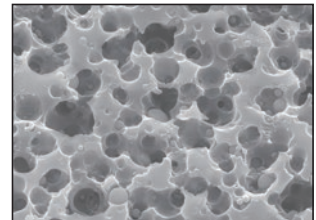


### CIRCUPOSIT™ 7800 Desmear Process and CIRCUPOSIT™ ADV 8550 Electroless Copper

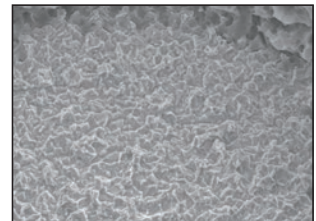
#### Advantage of Process 新製程具備以下卓越之特性

- High peel strength and optimum surface roughness for insulator adhesion  
抗拉撕强度高, 對於絕緣層的貼合表面有最理想的粗糙度
- Uniform and stable adhesion promotion treatment and reliable via bottom cleaning  
能提升均勻且穩定的表面結合能力及對於盲孔孔底有可靠的清潔能力
- Excellent plating coverage of electroless copper on insulator, especially at the bottom of vias  
優越的鍍層覆蓋能力, 使化學沉銅均勻地覆蓋在絕緣層表面及盲孔底部
- Rochel salt type E'less Cu plate for Semi-Additive Process. (EDTA free)  
針對半加成製程所開發的酒石酸系化學沉銅 (EDTA free)
- Applying Alkaline Ionic Catalyst system which does not required PRE-DIP solution.  
可搭配新開發的鹼性離子鈹系統, 且不需要預浸流程。
- High speed deposition with excellent bath stability.  
沉積速率快且槽液穩定性亦高
- Pure Copper metal deposition without affect to flash etching speed.  
純銅金屬沉積, 不影響後段線路蝕刻速率

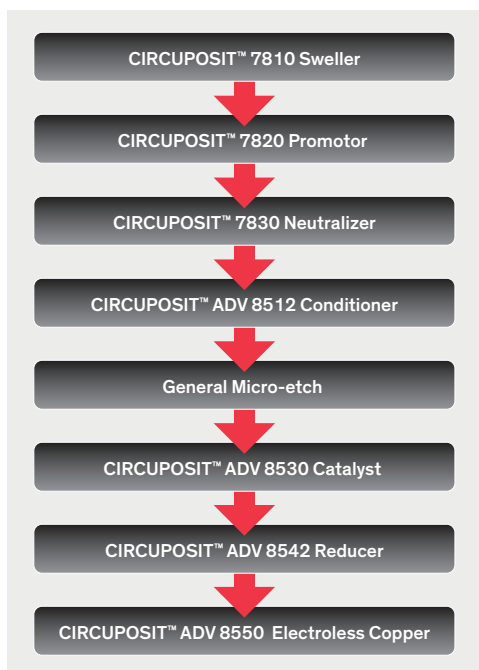
Adhesion promotion on insulator  
絕緣層表面的理想粗糙度



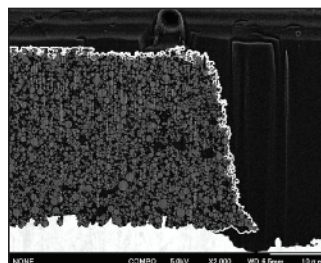
Via bottom cleaning  
清潔的盲孔底部



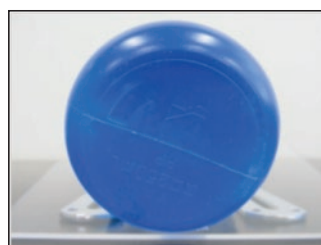
#### Process 製程



Excellent Plating uniformity on Microvia  
優良的沉積均勻度於盲孔內



Achieve excellent bath stability with high deposition speed with Rochel salt base E'less Copper plate bath formulation  
新酒石酸型化學銅, 其沉積速率快且槽液穩定性亦高



Stable adhesion on Low Ra insulator materials  
即使在低 Ra 值的表面, 仍具有優異且穩定的附著力表現。

